

Now Available!

THE WORLDWIDE IC PACKAGING MARKET

2011 EDITION

**The Most Comprehensive Report Available
On The Global IC Packaging Industry**

Report Highlights

- **Industry Overview**
 - ◆ Update on Japan
 - ◆ Semiconductor Industry Analysis
- **Worldwide IC Packaging Market Forecasts, 2009–2015**
 - ◆ Units
 - ◆ Package Prices
 - ◆ Packaging Revenue
 - ◆ By Semiconductor Product
 - ◆ By Package Family
 - ◆ By I/O Range
- **Contract IC Packaging Market Forecasts, 2009–2015**
 - ◆ Units
 - ◆ Package Prices
 - ◆ Packaging Revenue
 - ◆ Competitive Rankings
 - ◆ Company Profiles

New Venture Research Corp.

337 Clay St., Suite 101

Nevada City, CA 95959

www.newventureresearch.com

A Technology Market Research Company

kwilliams@newventureresearch.com

Tel: (408) 244-1100

Fax: (408) 864-2138

The Worldwide IC Packaging Market, 2011 Edition

Synopsis

The semiconductor industry's recovery in 2010 following the 2008-2009 recession was unprecedented, with one of the best growth years in its history. The estimated worldwide IC growth was 28.9% in terms of units and 31.3% in terms of revenue. Demand is being driven by wireless portable devices such as the iPhone and iPad which is far exceeding the growth of the overall economy.

New Venture Research (NVR), in the **2011 Edition of The Worldwide IC Packaging Market**, analyzes the semiconductor industry and uses this analysis to forecast the future of the global IC packaging market.

The report begins with the latest updates on Japan, mergers and acquisitions, historic and future unit and revenue graphs, and a SATS company overview.

Following this high-level review, the report presents forecasts for each semiconductor product type, and segments these products by package family and I/O count range. Packaging revenue figures are displayed for each segment, based on prices charged in the contract assembly market. The package families are then rolled up by I/O count and semiconductor product. In doing so, the report generates the total value of the IC packaging industry.

Next, the report presents NVR's continuing, extensive coverage of the packaging contractor market. Packaging contractors will continue to assume a larger share of the world's IC packaging business. The report breaks the contractor market down by package families and major product categories providing units and revenue for each category. To help you further assess this group of companies, the report profiles the activities of the world's largest contractors and the packages they offer.

The Worldwide IC Packaging Market, 2011 Edition continues NVR's leadership position in assessing the status and future of IC packaging. This report will provide you with an effective and economical tool for assessing the future of this market. The report sells for \$2995 and is delivered by email as a single-user PDF file. Extra single-user licenses sell for \$250 each and a corporate license is \$1000. With the purchase of the report, an Excel spreadsheet of all tables may be obtained for an additional \$500.

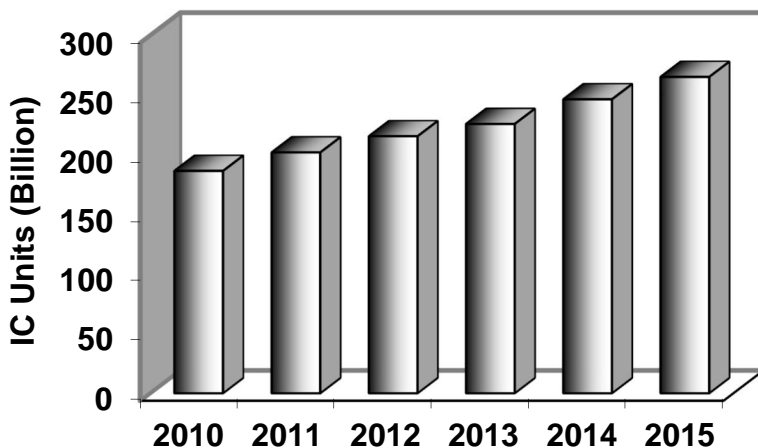


Figure 1 IC Unit Forecast

About the Author

Sandra Winkler is the senior analyst for IC packaging at New Venture Research (NVR). She began her analyst career as an independent consultant to the telecommunications industry more than 20 years ago. Ms. Winkler has authored widely cited reports on IC packaging since 1995 for Electronic Trend Publications (ETP) which is now NVR. She has spoken at numerous industry conferences and has written articles for a variety of trade publications. Ms. Winkler has an MBA from Santa Clara University.

The Worldwide IC Packaging Market, 2011 Edition

Table of Contents

Chapter 1: Introduction

Chapter 2: Executive Summary

Chapter 3: The State of the Industry

Feeling the Affects of the Tsunami

Acquisitions and Mergers

The Cycles of Life

SATs Company Overview

Chapter 4: IC Package Forecast by Product

MPU

MCU

DSP

DRAM

Flash

SRAM

ROM and EPROM

EEPROM/Other Memory

Digital Bipolar

Standard Logic

Gate Arrays

Cell-Based and PLD

Display Drivers

Custom Logic

Amplifiers

Interfaces

Voltage Regulators

Data Converters

Custom Analog

Chapter 5:

IC Package Forecast by Package Family

DIP

SOT

SO

TSOP

DFN

CC

QFP

QFN

PGA

BGA

FBGA

WLP

DCA

Chapter 6: Packaging Contractor Market

Market Overview

Forecasts by Package Family

DIP

SOT

SO

TSOP

DFN

CC

QFP

QFN

PGA

BGA

FBGA

WLP

Unit, Revenue, and Pricing Forecasts

Forecast by Product

Contractor Rankings

Chapter 7: Company Profiles

Amkor

Anst China

ASE

Azimuth

Carsem

China Wafer Level CSP

ChipMOS

CORWIL Technology

EEMS

FlipChip Int'l

Hana

Hana Micron

I2A

IDS Electronics

Infiniti

Jiangsu Changjiang

Lingsen

Millennium Microtech

Naito Densai Kogyo

Nantong Fujitsu

NxGEN

OSE

Powertech

Shinko Electric

Signetics

Siliconware

SPEL

STATS ChipPAC

Tianshui Huatian Tech

Unisem

UTAC

Vigilant Technology

XinTec

Appendix A: Contractor Packages

Appendix B: Contractor Website Guide

Appendix C: Glossary

The Worldwide IC Packaging Market, 2011 Edition

Table of Contents (continued)

Partial List of Figures and Tables

IC Unit Forecast
IC Revenue Forecast
IC Packaging Revenue Forecast
Price per I/O by Package Family
Package Price Forecasts
IC Product Forecasts
 MPU
 MCU
 DSP
 DRAM
 Flash
 SRAM
 ROM and EPROM
 EEPROM/Other Memory
 Digital Bipolar
 Standard Logic
 Gate Arrays
 Cell-Based and PLD
 Display Drivers
 Custom Logic
 Amplifiers
 Interfaces
 Voltage Regulators
 Data Converters
 Custom Analog

DIP Forecasts—3 I/O Ranges
SOT Forecasts
SO Forecasts—3 I/O Ranges
TSOP Forecasts—3 I/O Ranges
DFN Forecasts—2 I/O Ranges
CC Forecasts—2 I/O Ranges
QFP Forecasts—2 I/O Ranges
QFN Forecasts—4 I/O Ranges
PGA Forecasts—2 I/O Ranges
BGA Forecasts—3 I/O Ranges
FBGA Forecasts—5 I/O Ranges
WLP Forecasts—4 I/O Ranges
DCA Forecasts—5 I/O Ranges
Total IC Packaging Revenue

Contractor Total Forecast
Contractor DIP Forecast
Contractor SOT Forecast
Contractor SO Forecast
Contractor TSOP Forecast
Contractor DFN Forecast
Contractor CC Forecast
Contractor QFP Forecast
Contractor QFN Forecast
Contractor PGA Forecast
Contractor BGA Forecast
Contractor FBGA Forecast
Contractor WLP Forecast
Packaging Contractor Rankings

Published May 2011 - 425 Pages

Order Form

Payment Method

Check in the amount of \$ _____ is enclosed.

Invoice per P.O. # _____

Please charge: Visa MasterCard American Express

Card # _____ Exp. _____

Name On Card _____

Signature _____ Date _____

Name _____

Title _____

Company _____

Address _____

City/State/Zip _____

Telephone _____

Fax _____

E-mail _____

The Worldwide IC Packaging Market, 2011 Edition (Single-User License - PDF file)

\$2995

Add Extra Single-User Licenses (\$250 each) or Corporate License (\$1,000)

Returns: No return privileges. **International Orders:** Must be prepaid, please contact us for payment arrangements.

New Venture Research Corp.

337 Clay St., Suite 101
Nevada City, CA 95959

Tel: (408) 244-1100 Fax: (408) 864-2138

www.newventureresearch.com; kwilliams@newventureresearch.com

	Subtotal	
	TOTAL	